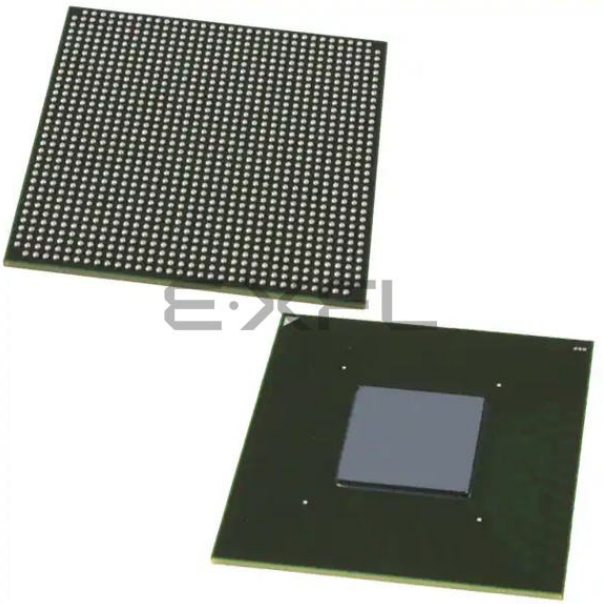

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The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	17110
Number of Logic Elements/Cells	362000
Total RAM Bits	19822592
Number of I/O	544
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA Exposed Pad
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxfb3h4f35c4g

Symbol	Description	Condition (V)	Overshoot Duration as % of High Time	Unit
Vi (AC)	AC input voltage	3.8	100	%
		3.85	68	%
		3.9	45	%
		3.95	28	%
		4	15	%
		4.05	13	%
		4.1	11	%
		4.15	9	%
		4.2	8	%
		4.25	7	%
		4.3	5.4	%
		4.35	3.2	%
		4.4	1.9	%
		4.45	1.1	%
		4.5	0.6	%
		4.55	0.4	%
		4.6	0.2	%

Recommended Operating Conditions

This section lists the functional operation limits for the AC and DC parameters for Arria V devices.

Recommended Operating Conditions

Table 1-3: Recommended Operating Conditions for Arria V Devices

This table lists the steady-state voltage values expected from Arria V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Symbol	Description	Condition	Minimum[1]	Typical	Maximum[1]	Unit
V_{CC}	Core voltage power supply	–C4, –I5, –C5, –C6	1.07	1.1	1.13	V
		–I3	1.12	1.15	1.18	V
V_{CCP}	Periphery circuitry, PCIe hard IP block, and transceiver PCS power supply	–C4, –I5, –C5, –C6	1.07	1.1	1.13	V
		–I3	1.12	1.15	1.18	V
V_{CCPGM}	Configuration pins power supply	3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V
		1.8 V	1.71	1.8	1.89	V
V_{CC_AUX}	Auxiliary supply	—	2.375	2.5	2.625	V
V_{CCBAT}[2]	Battery back-up power supply (For design security volatile key register)	—	1.2	—	3.0	V
V_{CCPD}[3]	I/O pre-driver power supply	3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V

(1) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.
(2) If you do not use the design security feature in Arria V devices, connect V_{CCBAT} to a 1.5-V, 2.5-V, or 3.0-V power supply. Arria V power-on reset (POR) circuitry monitors V_{CCBAT}. Arria V devices do not exit POR if V_{CCBAT} is not powered up.
(3) V_{CCPD} must be 2.5 V when V_{CCIO} is 2.5, 1.8, 1.5, 1.35, 1.25, or 1.2 V. V_{CCPD} must be 3.0 V when V_{CCIO} is 3.0 V. V_{CCPD} must be 3.3 V when V_{CCIO} is 3.3 V.

Symbol	Description	Condition (V)	Calibration Accuracy			Unit
			–I3, –C4	–I5, –C5	–C6	
60-Ω and 120-Ω R_T	Internal parallel termination with calibration (60-Ω and 120-Ω setting)	V_{CCIO} = 1.2	–10 to +40	–10 to +40	–10 to +40	%
25-Ω $R_{S\_left\_shift}$	Internal left shift series termination with calibration (25-Ω $R_{S\_left\_shift}$ setting)	V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2	±15	±15	±15	%

OCT Without Calibration Resistance Tolerance Specifications

Table 1-9: OCT Without Calibration Resistance Tolerance Specifications for Arria V Devices

This table lists the Arria V OCT without calibration resistance tolerance to PVT changes.

Symbol	Description	Condition (V)	ResistanceTolerance			Unit
			–I3, –C4	–I5, –C5	–C6	
25-Ω R_S	Internal series termination without calibration (25-Ω setting)	V_{CCIO} = 3.0, 2.5	±30	±40	±40	%
25-Ω R_S	Internal series termination without calibration (25-Ω setting)	V_{CCIO} = 1.8, 1.5	±30	±40	±40	%
25-Ω R_S	Internal series termination without calibration (25-Ω setting)	V_{CCIO} = 1.2	±35	±50	±50	%
50-Ω R_S	Internal series termination without calibration (50-Ω setting)	V_{CCIO} = 3.0, 2.5	±30	±40	±40	%
50-Ω R_S	Internal series termination without calibration (50-Ω setting)	V_{CCIO} = 1.8, 1.5	±30	±40	±40	%
50-Ω R_S	Internal series termination without calibration (50-Ω setting)	V_{CCIO} = 1.2	±35	±50	±50	%
100-Ω R_D	Internal differential termination (100-Ω setting)	V_{CCIO} = 2.5	±25	±40	±40	%

I/O Standard	$V_{IL(DC)}$ (V)		$V_{IH(DC)}$ (V)		$V_{IL(AC)}$ (V)	$V_{IH(AC)}$ (V)	V_{OL} (V)	V_{OH} (V)	I_{OL}[14] (mA)	I_{OH}[14] (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
HSTL-15 Class II	—	V_{REF} – 0.1	V_{REF} + 0.1	—	V_{REF} – 0.2	V_{REF} + 0.2	0.4	V_{CCIO} – 0.4	16	–16
HSTL-12 Class I	–0.15	V_{REF} – 0.08	V_{REF} + 0.08	V_{CCIO} + 0.15	V_{REF} – 0.15	V_{REF} + 0.15	0.25 × V_{CCIO}	0.75 × V_{CCIO}	8	–8
HSTL-12 Class II	–0.15	V_{REF} – 0.08	V_{REF} + 0.08	V_{CCIO}+ 0.15	V_{REF} – 0.15	V_{REF} + 0.15	0.25 × V_{CCIO}	0.75 × V_{CCIO}	16	–16
HSUL-12	—	V_{REF} – 0.13	V_{REF} + 0.13	—	V_{REF} – 0.22	V_{REF} + 0.22	0.1 × V_{CCIO}	0.9 × V_{CCIO}	—	—

Differential SSTL I/O Standards

Table 1-17: Differential SSTL I/O Standards for Arria V Devices

I/O Standard	V_{CCIO} (V)			$V_{SWING(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{SWING(AC)}$ (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.3	V_{CCIO} + 0.6	$V_{CCIO}/2$ – 0.2	—	$V_{CCIO}/2$ + 0.2	0.62	V_{CCIO} + 0.6
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	V_{CCIO} + 0.6	$V_{CCIO}/2$ – 0.175	—	$V_{CCIO}/2$ + 0.175	0.5	V_{CCIO} + 0.6
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	[15]	$V_{CCIO}/2$ – 0.15	—	$V_{CCIO}/2$ + 0.15	$2(V_{IH(AC)} - V_{REF})$	$2(V_{IL(AC)} - V_{REF})$
SSTL-135	1.283	1.35	1.45	0.18	[15]	$V_{CCIO}/2$ – 0.15	$V_{CCIO}/2$	$V_{CCIO}/2$ + 0.15	$2(V_{IH(AC)} - V_{REF})$	$2(V_{IL(AC)} - V_{REF})$

(14) To meet the I_{OL} and I_{OH} specifications, you must set the current strength settings accordingly. For example, to meet the SSTL15CI specification (8 mA), you should set the current strength settings to 8 mA. Setting at lower current strength may not meet the I_{OL} and I_{OH} specifications in the datasheet.

(15) The maximum value for $V_{SWING(DC)}$ is not defined. However, each single-ended signal needs to be within the respective single-ended limits ($V_{IH(DC)}$ and $V_{IL(DC)}$).

Table 1-21: Transceiver Clocks Specifications for Arria V GX and SX Devices

Symbol/Description	Condition	Transceiver Speed Grade 4			Transceiver Speed Grade 6			Unit
		Min	Typ	Max	Min	Typ	Max	
`fixedclk` clock frequency	PCIe Receiver Detect	—	125	—	—	125	—	MHz
Transceiver Reconfiguration Controller IP (`mgmt_clk_clk`) clock frequency	—	75	—	125	75	—	125	MHz

Table 1-22: Receiver Specifications for Arria V GX and SX Devices

Symbol/Description	Condition	Transceiver Speed Grade 4			Transceiver Speed Grade 6			Unit
		Min	Typ	Max	Min	Typ	Max	
Supported I/O standards	1.5 V PCML, 2.5 V PCML, LVPECL, and LVDS							
Data rate[28]	—	611	—	6553.6	611	—	3125	Mbps
Absolute V_{MAX} for a receiver pin[29]	—	—	—	1.2	—	—	1.2	V
Absolute V_{MIN} for a receiver pin	—	–0.4	—	—	–0.4	—	—	V
Maximum peak-to-peak differential input voltage V_{ID} (diff p-p) before device configuration	—	—	—	1.6	—	—	1.6	V
Maximum peak-to-peak differential input voltage V_{ID} (diff p-p) after device configuration	—	—	—	2.2	—	—	2.2	V

(28) To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.
(29) The device cannot tolerate prolonged operation at this absolute maximum.

For example, when V_{OD} = 800 mV, the corresponding V_{OD} value setting is 40. The following conditions show that the 1st post tap pre-emphasis setting = 2 is valid:

- $|B| + |C| \leq 60 \rightarrow 40 + 2 = 42$
- $|B| - |C| > 5 \rightarrow 40 - 2 = 38$
- $(V_{MAX}/V_{MIN} - 1)\% < 600\% \rightarrow (42/38 - 1)\% = 10.52\%$

To predict the pre-emphasis level for your specific data rate and pattern, run simulations using the Arria V HSSI HSPICE models.

Table 1-33: Transmitter Pre-Emphasis Levels for Arria V Devices

Quartus Prime 1st Post Tap Pre-Emphasis Setting	Quartus Prime V_{OD} Setting							Unit
	10 (200 mV)	20 (400 mV)	30 (600 mV)	35 (700 mV)	40 (800 mV)	45 (900 mV)	50 (1000 mV)	
0	0	0	0	0	0	0	0	dB
1	1.97	0.88	0.43	0.32	0.24	0.19	0.13	dB
2	3.58	1.67	0.95	0.76	0.61	0.5	0.41	dB
3	5.35	2.48	1.49	1.2	1	0.83	0.69	dB
4	7.27	3.31	2	1.63	1.36	1.14	0.96	dB
5	—	4.19	2.55	2.1	1.76	1.49	1.26	dB
6	—	5.08	3.11	2.56	2.17	1.83	1.56	dB
7	—	5.99	3.71	3.06	2.58	2.18	1.87	dB
8	—	6.92	4.22	3.47	2.93	2.48	2.11	dB
9	—	7.92	4.86	4	3.38	2.87	2.46	dB
10	—	9.04	5.46	4.51	3.79	3.23	2.77	dB
11	—	10.2	6.09	5.01	4.23	3.61	—	dB
12	—	11.56	6.74	5.51	4.68	3.97	—	dB
13	—	12.9	7.44	6.1	5.12	4.36	—	dB
14	—	14.44	8.12	6.64	5.57	4.76	—	dB
15	—	—	8.87	7.21	6.06	5.14	—	dB

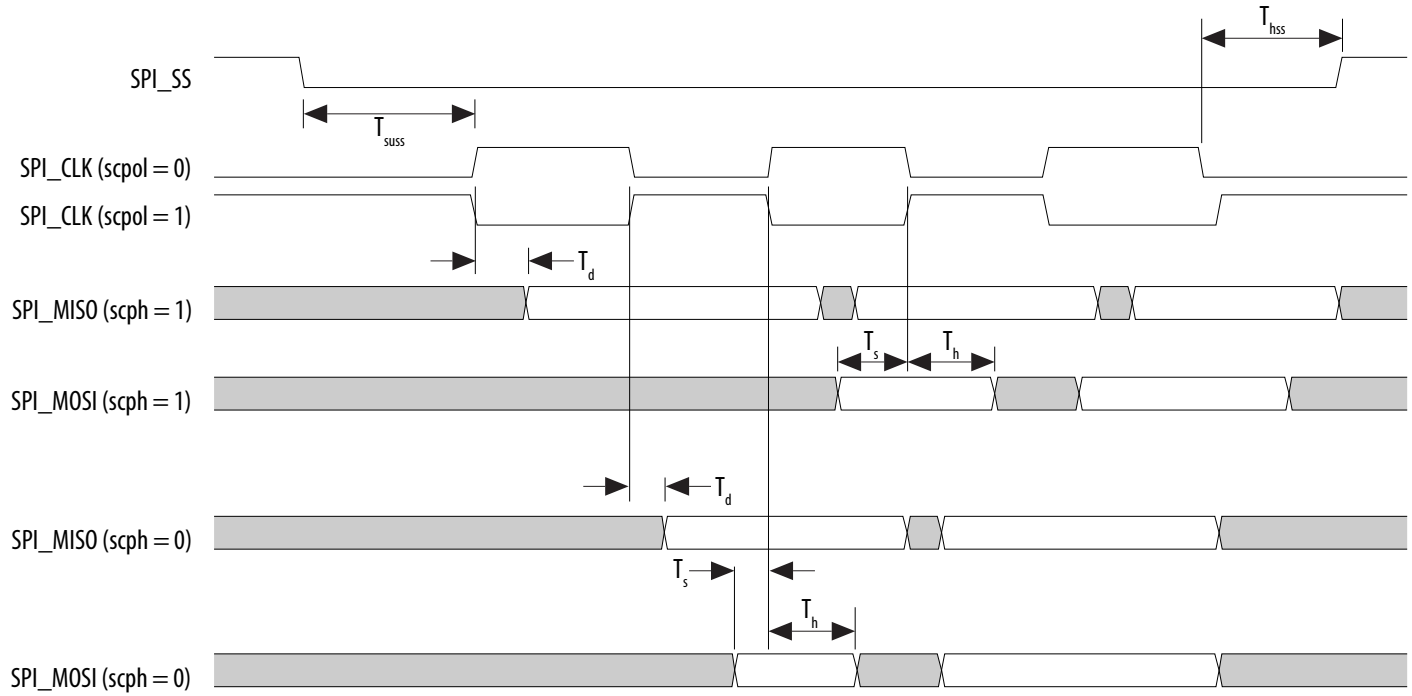
Symbol	Parameter	Condition	Min	Typ	Max	Unit
f_{OUT_EXT}	Output frequency for external clock output	–3 speed grade	—	—	670[63]	MHz
		–4 speed grade	—	—	670[63]	MHz
		–5 speed grade	—	—	622[63]	MHz
		–6 speed grade	—	—	500[63]	MHz
$t_{OUTDUTY}$	Duty cycle for external clock output (when set to 50%)	—	45	50	55	%
t_{FCOMP}	External feedback clock compensation time	—	—	—	10	ns
$t_{DYCONFIGCLK}$	Dynamic configuration clock for `mgmt_clk` and `scanclk`	—	—	—	100	MHz
t_{LOCK}	Time required to lock from end-of-device configuration or deassertion of `areset`	—	—	—	1	ms
t_{DLOCK}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	—	—	—	1	ms
f_{CLBW}	PLL closed-loop bandwidth	Low	—	0.3	—	MHz
		Medium	—	1.5	—	MHz
		High[64]	—	4	—	MHz
t_{PLL_PSERR}	Accuracy of PLL phase shift	—	—	—	±50	ps
t_{ARESET}	Minimum pulse width on the `areset` signal	—	10	—	—	ns
t_{INCCJ}[65][66]	Input clock cycle-to-cycle jitter	$F_{REF} \geq 100$ MHz	—	—	0.15	UI (p-p)
		$F_{REF} < 100$ MHz	—	—	±750	ps (p-p)

(64) High bandwidth PLL settings are not supported in external feedback mode.
(65) A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source with jitter < 120 ps.
(66) F_{REF} is f_{IN}/N, specification applies when $N = 1$.

Symbol	Condition	–I3, –C4			–I5, –C5			–C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
	SERDES factor J ≥ 8[76][78], LVDS TX with RX DPA	[77]	—	1600	[77]	—	1500	[77]	—	1250	Mbps
	SERDES factor J = 1 to 2, Uses DDR Registers	[77]	—	[79]	[77]	—	[79]	[77]	—	[79]	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Network - f_{HSDR} (data rate)[80]	SERDES factor J = 4 to 10[81]	[77]	—	945	[77]	—	945	[77]	—	945	Mbps
Emulated Differential I/O Standards with One External Output Resistor Network - f_{HSDR} (data rate)[80]	SERDES factor J = 4 to 10[81]	[77]	—	200	[77]	—	200	[77]	—	200	Mbps
$t_{x\ Jitter}$ -True Differential I/O Standards	Total Jitter for Data Rate 600 Mbps – 1.25 Gbps	—	—	160	—	—	160	—	—	160	ps
	Total Jitter for Data Rate < 600 Mbps	—	—	0.1	—	—	0.1	—	—	0.1	UI

(78) The V_{CC} and V_{CCP} must be on a separate power layer and a maximum load of 5 pF for chip-to-chip interface.
(79) The maximum ideal data rate is the SERDES factor (J) x the PLL maximum output frequency (f_{OUT}), provided you can close the design timing and the signal integrity simulation is clean.
(80) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine the leftover timing margin.
(81) When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.

Figure 1-10: SPI Slave Timing Diagram



Related Information

SPI Controller, Arria V Hard Processor System Technical Reference Manual
Provides more information about rx_sample_delay.

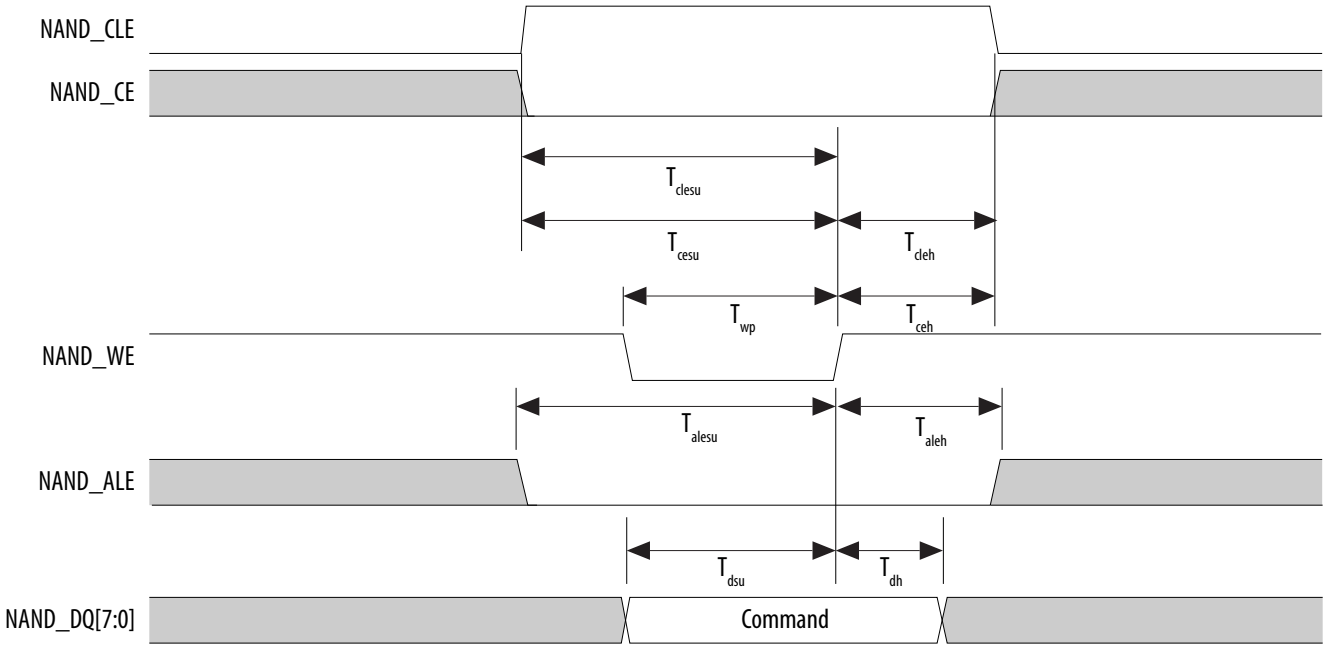
SD/MMC Timing Characteristics

Table 1-54: Secure Digital (SD)/MultiMediaCard (MMC) Timing Requirements for Arria V Devices

After power up or cold reset, the Boot ROM uses `drvsel` = 3 and `smplsel` = 0 to execute the code. At the same time, the SD/MMC controller enters the Identification Phase followed by the Data Phase. During this time, the value of interface output clock `SDMMC_CLK_OUT` changes from a maximum of 400 kHz (Identification Phase) up to a maximum of 12.5 MHz (Data Phase), depending on the internal reference clock `SDMMC_CLK` and the `CSEL` setting. The value of `SDMMC_CLK` is based on the external oscillator frequency and has a maximum value of 50 MHz.

Symbol	Description	Min	Max	Unit
T_{dh} (89)	Data to write enable hold time	5	—	ns
T_{cea}	Chip enable to data access time	—	25	ns
T_{rea}	Read enable to data access time	—	16	ns
T_{rhz}	Read enable to data high impedance	—	100	ns
T_{rr}	Ready to read enable low	20	—	ns

Figure 1-17: NAND Command Latch Timing Diagram



Related Information

- **PS Configuration Timing** on page 1-81
- **AS Configuration Timing**
  Provides the AS configuration timing waveform.

DCLK Frequency Specification in the AS Configuration Scheme

Table 1-69: DCLK Frequency Specification in the AS Configuration Scheme

This table lists the internal clock frequency specification for the AS configuration scheme. The DCLK frequency specification applies when you use the internal oscillator as the configuration clock source. The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Parameter	Minimum	Typical	Maximum	Unit
DCLK frequency in AS configuration scheme	5.3	7.9	12.5	MHz
	10.6	15.7	25.0	MHz
	21.3	31.4	50.0	MHz
	42.6	62.9	100.0	MHz

PS Configuration Timing

Table 1-70: PS Timing Parameters for Arria V Devices

Symbol	Parameter	Minimum	Maximum	Unit
t_{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t_{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t_{CFG}	nCONFIG low pulse width	2	—	µs
t_{STATUS}	nSTATUS low pulse width	268	1506(103)	µs
t_{CF2ST1}	nCONFIG high to nSTATUS high	—	1506(104)	µs

(103) You can obtain this value if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
(104) You can obtain this value if you do not delay configuration by externally holding nSTATUS low.

Date	Version	Changes

December 2015	2015.12.16	• Updated Quad Serial Peripheral Interface (SPI) Flash Timing Requirements for Arria V Devices table.
		  • Updated F_{clk}, $T_{dutycycle}$, and $T_{dssfrst}$ specifications.
		  • Added T_{qspi_clk}, T_{din_start}, and T_{din_end} specifications.
		  • Removed T_{dinmax} specifications.
		• Updated the minimum specification for T_{clk} to 16.67 ns and removed the maximum specification in SPI Master Timing Requirements for Arria V Devices table.
		• Updated Secure Digital (SD)/MultiMediaCard (MMC) Timing Requirements for Arria V Devices table.
		  • Updated T_{clk} to $T_{sdmmc\_clk\_out}$ symbol.
		  • Updated $T_{sdmmc\_clk\_out}$ and T_{d} specifications.
		  • Added T_{sdmmc_clk}, T_{su}, and T_{h} specifications.
		  • Removed T_{dinmax} specifications.
		• Updated the following diagrams:
		  • Quad SPI Flash Timing Diagram
		  • SD/MMC Timing Diagram
		• Updated configuration .rbf sizes for Arria V devices.
		• Changed instances of *Quartus II* to *Quartus Prime*.

The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% of the duty cycle.

For example, a signal that overshoots to 3.95 V can be at 3.95 V for only ~21% over the lifetime of the device; for a device lifetime of 10 years, the overshoot duration amounts to ~2 years.

Table 2-4: Maximum Allowed Overshoot During Transitions for Arria V GZ Devices

Symbol	Description	Condition (V)	Overshoot Duration as % @ T_J = 100°C	Unit
Vi (AC)	AC input voltage	3.8	100	%
		3.85	64	%
		3.9	36	%
		3.95	21	%
		4	12	%
		4.05	7	%
		4.1	4	%
		4.15	2	%
		4.2	1	%

Recommended Operating Conditions

Table 2-5: Recommended Operating Conditions for Arria V GZ Devices

Power supply ramps must all be strictly monotonic, without plateaus.

Symbol	Description	Condition	Minimum(114)	Typical	Maximum (114)	Unit
V_{CC}	Core voltage and periphery circuitry power supply (115)	—	0.82	0.85	0.88	V

(114) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

(115) The V_{CC} core supply must be set to 0.9 V if the Partial Reconfiguration (PR) feature is used.

Hot Socketing

Table 2-14: Hot Socketing Specifications for Arria V GZ Devices

Symbol	Description	Maximum
$I_{IOPIN\ (DC)}$	DC current per I/O pin	300 µA
$I_{IOPIN\ (AC)}$	AC current per I/O pin	8 mA (124)
$I_{XCVR\text{-}TX\ (DC)}$	DC current per transceiver transmitter pin	100 mA
$I_{XCVR\text{-}RX\ (DC)}$	DC current per transceiver receiver pin	50 mA

Internal Weak Pull-Up Resistor

Table 2-15: Internal Weak Pull-Up Resistor for Arria V GZ Devices

All I/O pins have an option to enable the weak pull-up resistor except the configuration, test, and JTAG pins. The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately 25 kΩ .

Symbol	Description	V_{CCIO} Conditions (V) (125)	Value (126)	Unit
R_{PU}	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if you enable the programmable pull-up resistor option.	3.0 ±5%	25	k Ω
		2.5 ±5%	25	k Ω
		1.8 ±5%	25	k Ω
		1.5 ±5%	25	kΩ
		1.35 ±5%	25	k Ω
		1.25 ±5%	25	k Ω
		1.2 ±5%	25	k Ω

(124) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{IOPIN}| = C\ dv/dt$, in which C is the I/O pin capacitance and dv/dt is the slew rate.
(125) The pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO}.
(126) These specifications are valid with a ±10% tolerance to cover changes over PVT.

I/O Standard Specifications

The V_{OL} and V_{OH} values are valid at the corresponding I_{OH} and I_{OL}, respectively.

Table 2-16: Single-Ended I/O Standards for Arria V GZ Devices

I/O Standard	V_{CCIO} (V)			V_{IL} (V)		V_{IH} (V)		V_{OL} (V)	V_{OH} (V)	I_{OL} (mA)	I_{OH} (mA)
	Min	Typ	Max	Min	Max	Min	Max	Max	Min		
LVTTL	2.85	3	3.15	–0.3	0.8	1.7	3.6	0.4	2.4	2	–2
LVCMOS	2.85	3	3.15	–0.3	0.8	1.7	3.6	0.2	V_{CCIO} – 0.2	0.1	–0.1
2.5 V	2.375	2.5	2.625	–0.3	0.7	1.7	3.6	0.4	2	1	–1
1.8 V	1.71	1.8	1.89	–0.3	0.35 × V_{CCIO}	0.65 × V_{CCIO}	V_{CCIO} + 0.3	0.45	V_{CCIO} – 0.45	2	–2
1.5 V	1.425	1.5	1.575	–0.3	0.35 × V_{CCIO}	0.65 × V_{CCIO}	V_{CCIO} + 0.3	0.25 × V_{CCIO}	0.75 × V_{CCIO}	2	–2
1.2 V	1.14	1.2	1.26	–0.3	0.35 × V_{CCIO}	0.65 × V_{CCIO}	V_{CCIO} + 0.3	0.25 × V_{CCIO}	0.75 × V_{CCIO}	2	–2

Table 2-17: Single-Ended SSTL, HSTL, and HSUL I/O Reference Voltage Specifications for Arria V GZ Devices

I/O Standard	V_{CCIO} (V)			V_{REF} (V)			V_{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.49 × V_{CCIO}	0.5 × V_{CCIO}	0.51 × V_{CCIO}	V_{REF} – 0.04	V_{REF}	V_{REF} + 0.04
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	V_{REF} – 0.04	V_{REF}	V_{REF} + 0.04
SSTL-15 Class I, II	1.425	1.5	1.575	0.49 × V_{CCIO}	0.5 × V_{CCIO}	0.51 × V_{CCIO}	0.49 × V_{CCIO}	0.5 × VCCIO	0.51 × V_{CCIO}

Symbol/Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Maximum peak-to-peak differential input voltage V_{ID} (diff p-p) before device configuration	—	—	—	1.6	—	—	1.6	V
Maximum peak-to-peak differential input voltage V_{ID} (diff p-p) after device configuration (146)	V_{CCR_GXB} = 1.0 V (V_{ICM} = 0.75 V)	—	—	1.8	—	—	1.8	V
	V_{CCR_GXB} = 0.85 V (V_{ICM} = 0.6 V)	—	—	2.4	—	—	2.4	V
Minimum differential eye opening at receiver serial input pins (147)(148)	—	85	—	—	85	—	—	mV
Differential on-chip termination resistors	85–Ω setting	—	85 ± 30%	—	—	85 ± 30%	—	Ω
	100–Ω setting	—	100 ± 30%	—	—	100 ± 30%	—	Ω
	120–Ω setting	—	120 ± 30%	—	—	120 ± 30%	—	Ω
	150–Ω setting	—	150 ± 30%	—	—	150 ± 30%	—	Ω

(146) The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to 4 × (absolute V_{MAX} for receiver pin - V_{ICM}).

(147) The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.

(148) Minimum eye opening of 85 mV is only for the unstressed input eye condition.

Symbol/Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
V_{ICM} (AC and DC coupled)	V_{CCR_GXB} = 0.85 V full bandwidth	—	600	—	—	600	—	mV
	V_{CCR_GXB} = 0.85 V half bandwidth	—	600	—	—	600	—	mV
	V_{CCR_GXB} = 1.0 V full bandwidth	—	700	—	—	700	—	mV
	V_{CCR_GXB} = 1.0 V half bandwidth	—	700	—	—	700	—	mV
t_{LTR} (149)	—	—	—	10	—	—	10	µs
t_{LTD} (150)	—	4	—	—	4	—	—	µs
t_{LTD_manual} (151)	—	4	—	—	4	—	—	µs
$t_{LTR\_LTD\_manual}$ (152)	—	15	—	—	15	—	—	µs
Programmable equalization (AC Gain)	Full bandwidth (6.25 GHz) Half bandwidth (3.125 GHz)	—	—	16	—	—	16	dB

(149) t_{LTR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
(150) t_{LTD} is time required for the receiver CDR to start recovering valid data after the `rx_is_lockedtodata` signal goes high.
(151) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the `rx_is_lockedtodata` signal goes high when the CDR is functioning in the manual mode.
(152) $t_{LTR\_LTD\_manual}$ is the time the receiver CDR must be kept in lock to reference (LTR) mode after the `rx_is_lockedtoref` signal goes high when the CDR is functioning in the manual mode.

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions (201)	Maximum
Parallel Rapid I/O	00001111	2	128	640 data transitions
	10010000	4	64	640 data transitions
Miscellaneous	10101010	8	32	640 data transitions
	01010101	8	32	640 data transitions

Soft CDR Mode High-Speed I/O Specifications

Table 2-44: High-Speed I/O Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.

Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Soft-CDR ppm tolerance	—	—	—	300	—	—	300	± ppm

(201) This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

Related Information

Configuration, Design Security, and Remote System Upgrades in Arria V Devices

Initialization

Table 2-61: Initialization Clock Source Option and the Maximum Frequency for Arria V GZ Devices

Initialization Clock Source	Configuration Schemes	Maximum Frequency (MHz)	Minimum Number of Clock Cycles
Internal Oscillator	AS, PS, FPP	12.5	8576
CLKUSR (222)	PS, FPP	125	
	AS	100	
DCLK	PS, FPP	125	

Configuration Files

Use the following table to estimate the file size before design compilation. Different configuration file formats, such as a hexadecimal file (`.hex`) or tabular text file (`.ttf`) format, have different file sizes.

For the different types of configuration file and file sizes, refer to the Quartus II software. However, for a specific version of the Quartus II software, any design targeted for the same device has the same uncompressed configuration file size.

(221) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the "Initialization" section of the *Configuration, Design Security, and Remote System Upgrades in Arria V Devices* chapter.

(222) To enable CLKUSR as the initialization clock source, turn on the **Enable user-supplied start-up clock (CLKUSR)** option in the Quartus II software from the **General** panel of the **Device and Pin Options** dialog box.

Table 2-62: Uncompressed .rbf Sizes for Arria V GZ Devices

Variant	Member Code	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) (223)
Arria V GZ	E1	137,598,880	562,208
	E3	137,598,880	562,208
	E5	213,798,880	561,760
	E7	213,798,880	561,760

Table 2-63: Minimum Configuration Time Estimation for Arria V GZ Devices

Variant	Member Code	Active Serial (224)			Fast Passive Parallel (225)		
		Width	DCLK (MHz)	Min Config Time (ms)	Width	DCLK (MHz)	Min Config Time (ms)
Arria V GZ	E1	4	100	344	32	100	43
	E3	4	100	344	32	100	43
	E5	4	100	534	32	100	67
	E7	4	100	534	32	100	67

Remote System Upgrades Circuitry Timing Specification

Table 2-64: Remote System Upgrade Circuitry Timing Specifications

Parameter	Minimum	Maximum	Unit
$t_{RU\_nCONFIG}$ (226)	250	—	ns
$t_{RU\_nRSTIMER}$ (227)	250	—	ns

(223) The IOCSR **.rbf** size is specifically for the Configuration via Protocol (CvP) feature.
(224) DCLK frequency of 100 MHz using external CLKUSR.
(225) Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.